GENERAL DESCRIPTION

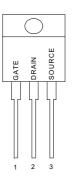
This high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power supplies, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

FEATURES

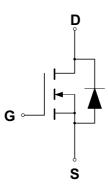
- Robust High Voltage Termination
- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- Diode is Characterized for Use in Bridge Circuits
- IDSS Specified at Elevated Temperature

PIN CONFIGURATION

TO-220/TO-220FP Front View



SYMBOL



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS

Rating		Value	Unit
Drain to Current – Continuous	I _D	6.0	A
- Pulsed	I _{DM}	18	
Gate-to-Source Voltage – Continue	V _{GS}	±20	V
 Non-repetitive 	V_{GSM}	±40	V
Total Power Dissipation	PD		W
TO-220		125	
TO-220FP		45	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to 150	°C
Single Pulse Drain-to-Source Avalanche Energy $-$ T _J = 25 $^\circ\!{ m C}$			mJ
$(V_{DD} = 100V, V_{GS} = 10V, I_L = 6A, L = 10mH, R_G = 25\Omega)$	E _{AS}	180	
Thermal Resistance – Junction to Case	θ _{JC}	1.0	°C <i>I</i> W
 Junction to Ambient 	θ _{JA}	62.5	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T∟	260	°C

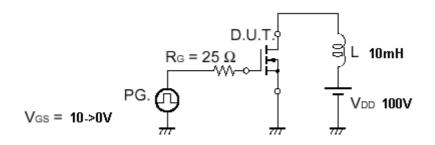
(1) VDD = 50V, ID = 6A

(2) Pulse Width and frequency is limited by $T_{J(max)}$ and thermal response

ORDERING INFORMATION

Part Number Package	
IRF6N60	TO-220
IRF6N60FP	TO-220 Full Pak

TEST CIRCUIT



Test Circuit – Avalanche Capability

ELECTRICAL CHARACTERISTICS

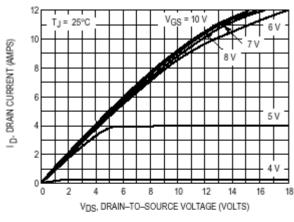
Unless otherwise specified, T_J = 25 $^\circ\!\mathrm{C}$.

				IRF6N60		
Characteristic		Symbol	Min	Тур	Max	Units
Drain-Source Breakdown Voltage		V _{(BR)DSS}	600			V
$(V_{GS} = 0 V, I_D = 250 \mu A)$						
Drain-Source Leakage Current		I _{DSS}				μA
$(V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V})$)				100	
$(V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125^{\circ}C)$					50	
Gate-Source Leakage Current-Forward		I _{GSSF}			100	nA
$(V_{gsf} = 20 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate-Source Leakage Current-Revers	e	I _{GSSR}			100	nA
$(V_{gsr} = 20 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate Threshold Voltage		V _{GS(th)}	2.0		4.0	V
$(V_{DS} = V_{GS}, I_D = 250 \ \mu A)$						
Static Drain-Source On-Resistance (V	_{GS} = 10 V, I _D = 3.5A) *	R _{DS(on)}			1.2	Ω
Forward Transconductance (V _{DS} = 15	V, I _D = 3.0A) *	g fs	3.4			mhos
Input Capacitance	$(V_{DS} = 25 V, V_{GS} = 0 V)$	C _{iss}		1498	2100	pF
Output Capacitance	$(v_{DS} - 25 v, v_{GS} - 0 v, f = 1.0 \text{ MHz})$	C _{oss}		158	220	pF
Reverse Transfer Capacitance		C _{rss}		29	60	pF
Turn-On Delay Time	$(V_{DD} = 300 \text{ V}, \text{ I}_{D} = 6.0 \text{ A}, \\ V_{GS} = 10 \text{ V}, \\ R_{G} = 9.1\Omega) \text{ *}$	t _{d(on)}		14	30	ns
Rise Time		t _r		19	40	ns
Turn-Off Delay Time		t _{d(off)}		40	80	ns
Fall Time		t _f		26	55	ns
Total Gate Charge	$(V_{DS} = 300 \text{ V}, I_D = 6.0 \text{ A}, V_{GS} = 10 \text{ V})^*$	Qg		35.5	50	nC
Gate-Source Charge		Q _{gs}		8.1		nC
Gate-Drain Charge		Q _{gd}		14.1		nC
Internal Drain Inductance		L _D		4.5		nH
(Measured from the drain lead 0.25"	from package to center of die)					
Internal Drain Inductance	ernal Drain Inductance			7.5		nH
(Measured from the source lead 0.2	5" from package to source bond pad)					
SOURCE-DRAIN DIODE CHARACTE	RISTICS					
Forward On-Voltage(1)	- (I _S = 6.0 A, d _{IS} /d _t = 100A/μs)	V _{SD}		0.83	1.2	V
Forward Turn-On Time		t _{on}		**		ns
Reverse Recovery Time		t _{rr}		266		ns

* Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%

** Negligible, Dominated by circuit inductance

TYPICAL ELECTRICAL CHARACTERISTICS





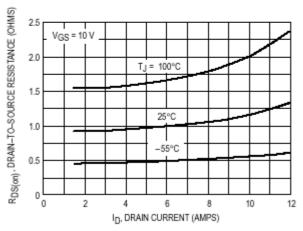


Figure 3. On–Resistance versus Drain Current and Temperature

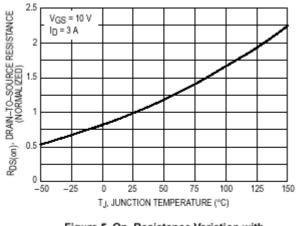


Figure 5. On–Resistance Variation with Temperature

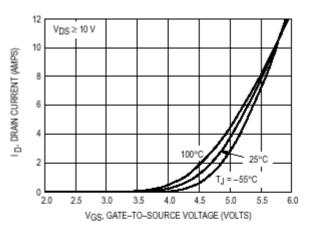


Figure 2. Transfer Characteristics

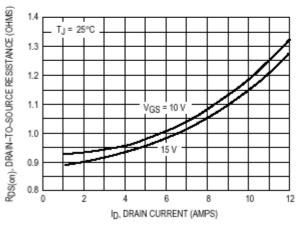


Figure 4. On–Resistance versus Drain Current and Gate Voltage

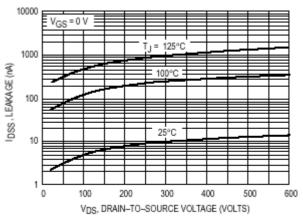


Figure 6. Drain–To–Source Leakage Current versus Voltage



IRF6N60 POWER MOSFET

